

LOW POWER PCIE GEN2/3 & QPI CLOCK FOR INTEL-BASED SERVERS

932SQL420

General Description

The 932SQL420 is a low power version of the CK420BQ synthesizer for Intel-based server platforms. The 932SQL420 is driven with a 25MHz crystal for maximum performance. It generates CPU outputs of 100Mhz. This device has a "low-drift" non-spread SAS/SRC PLL for use in systems that need to communicate across PCIe domains.

Recommended Application

Low Power CK420BQ

Key Specifications

- CPU, SRC, NS_SRC and NS_SAS cycle-cycle jitter <50ps
- Output to output skew <50ps
- Phase jitter: PCle Gen2 <2.7ps rms
- Phase jitter: QPI <0.3ps rms
- Phase jitter: NS-SAS <1.3ps rms using long period phase jitter method

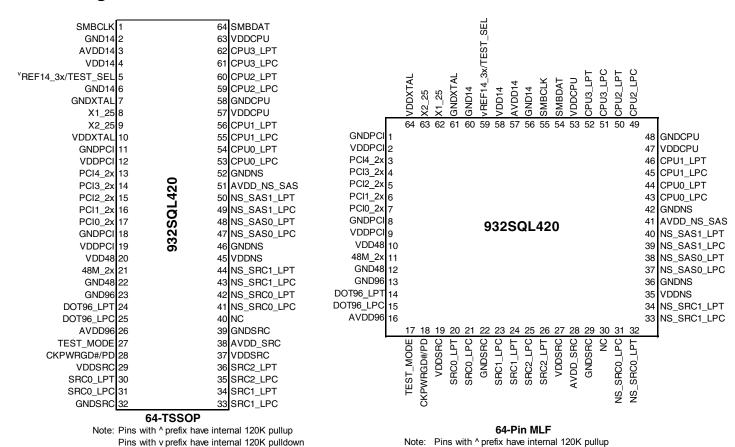
Features/Benefits

- 0.5% down spread capable on CPU, SRC and PCI outputs; reduce EMI
- Additional down spread amounts selectable via SMBus; maximal system flexibility
- 64-pin TSSOP and MLF packages; space savings

Output Features

- 4 Low-Power HCSL-compatible (LP-HCSL) CPU outputs
- 2 LP-HCSL NS_SAS outputs
- 2 LP-HCSL NS_SRC outputs
- 3 LP-HCSL SRC outputs
- 1 LP-HCSL DOT96 output
- 1 3.3V 48M output
- 5 3.3V PCI outputs
- 1 3.3V 14.318M output

PIn Configurations



Pins with v prefix have internal 120K pulldown

64TSSOP Pin Descriptions

PIN#	PIN NAME	TYPE	DESCRIPTION		
1	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant		
2	GND14	PWR	Ground pin for 14MHz output and logic.		
3	AVDD14	PWR	Analog power pin for 14MHz PLL		
4	VDD14	PWR	Power pin for 14MHz output and logic		
5	vREF14_3x/TEST_SEL	I/O	4.318 MHz reference clock. 3X drive strength as default / TEST_SEL latched input to enable est mode. Refer to Test Clarification Table. This pin has a weak (~120Kohm) internal pull down.		
6	GND14	PWR	Ground pin for 14MHz output and logic.		
7	GNDXTAL	PWR	Ground pin for Crystal Oscillator.		
8	X1_25	IN	Crystal input, Nominally 25.00MHz.		
9	X2_25	OUT	Crystal output, Nominally 25.00MHz.		
10	VDDXTAL	PWR	3.3V power for the crystal oscillator.		
11	GNDPCI	PWR	Ground pin for PCI outputs and logic.		
12	VDDPCI		3.3V power for the PCI outputs and logic		
13	PCI4_2x	OUT	3.3V PCI clock output		
14	PCI3_2x	OUT	3.3V PCI clock output		
15	PCI2_2x	OUT	3.3V PCI clock output		
16	PCI1_2x		3.3V PCI clock output		
17	PCI0_2x	OUT	3.3V PCI clock output		
18	GNDPCI		Ground pin for PCI outputs and logic.		
19	VDDPCI		3.3V power for the PCI outputs and logic		
20	VDD48		3.3V power for the 48MHz output and logic		
21	48M 2x		3.3V 48MHz output		
22	GND48		Ground pin for 48MHz output and logic.		
23	GND96		Ground pin for DOT96 output and logic.		
			True clock of low-power push-pull differential 96MHz output. External series resistors are needed		
24	DOT96_LPT	OUT	for termination.		
		_	Complementary clock of low-power push-pull differential 96MHz output. External series resistors		
25	DOT96_LPC	OUT	are needed for termination.		
26	AVDD96	PWR	3.3V power for the 48/96MHz PLL and the 96MHz output and logic		
			TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in test		
27	TEST_MODE	IN	mode. Refer to Test Clarification Table.		
			CKPWRGD# is an active low input used to sample latched inputs and allow the device to Power		
28	CKPWRGD#/PD	IN	Up. PD is an asynchronous active high input pin used to put the device into a low power state.		
			The internal clocks and PLLs are stopped.		
29	VDDSRC	PWR	3.3V power for the SRC outputs and logic		
			True clock of low-power push-pull differential SRC output. External series resistors are needed		
30	SRC0_LPT	OUT	for termination.		
	0000 100	O. 17	Complementary clock of low-power push-pull differential SRC output. External series resistors		
31	SRC0_LPC	OUT	are needed for termination.		
32	GNDSRC	PWR	Ground pin for SRC outputs and logic.		
			Complementary clock of low-power push-pull differential SRC output. External series resistors		
33	SRC1_LPC	OUT	are needed for termination.		
0.4	0004 107	O. 17	True clock of low-power push-pull differential SRC output. External series resistors are needed		
34	SRC1_LPT	OUT	for termination.		
6-	0000 100	O: :-	Complementary clock of low-power push-pull differential SRC output. External series resistors		
35	SRC2_LPC	OUT	are needed for termination.		
60	CDCC LDT	0::-	True clock of low-power push-pull differential SRC output. External series resistors are needed		
36	SRC2_LPT	OUT	for termination.		
37	VDDSRC	PWR	3.3V power for the SRC outputs and logic		
38	AVDD_SRC		3.3V power for the SRC PLL analog circuits		
39	GNDSRC		Ground pin for SRC outputs and logic.		
40	NC		No Connection.		
			Complementary clock of low-power push-pull differential non-spreading SRC output. External		
41	NS_SRC0_LPC	OUT	series resistors are needed for termination.		
40	NC CDC0 LDT	O. IT	True clock of low-power push-pull differential non-spreading SRC output. External series resistors		
42	NS_SRC0_LPT	OUT	are needed for termination.		
40	Ne epot Lpc	OUT	Complementary clock of low-power push-pull differential non-spreading SRC output. External		
43	NS_SRC1_LPC	OUT	series resistors are needed for termination.		
4.4	NO COCA LOT	O. IT	True clock of low-power push-pull differential non-spreading SRC output. External series resistors		
44	NS_SRC1_LPT	OUT	are needed for termination.		
45	VDDNS	PWR	3.3V power for the Non-Spreading differential outputs outputs and logic		
46	GNDNS		Ground pin for non-spreading differential outputs and logic.		

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64TSSOP Pin Descriptions (cont.)

PIN#	PIN NAME	TYPE	
47	NS_SAS0_LPC		Complementary clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.
48	NS_SAS0_LPT	OUT	True clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.
49	NS_SAS1_LPC	1 ()() 1	Complementary clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.
50	NS_SAS1_LPT	OUT	True clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.
51	AVDD_NS_SAS		3.3V power for the non-spreading SAS/SRC PLL analog circuits.
52	GNDNS	PWR	Ground pin for non-spreading differential outputs and logic.
53	CPU0_LPC	1 ()() 1	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
54	CPU0_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
55	CPU1_LPC	1 ()() 1	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
56	CPU1_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
57	VDDCPU	PWR	3.3V power for the CPU outputs and logic
58	GNDCPU	PWR	Ground pin for CPU outputs and logic.
59	CPU2_LPC	OUT	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
60	CPU2_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
61	CPU3_LPC	I OUI	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
62	CPU3_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.
63	VDDCPU	PWR	3.3V power for the CPU outputs and logic
64	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant

64MLF Pin Descriptions

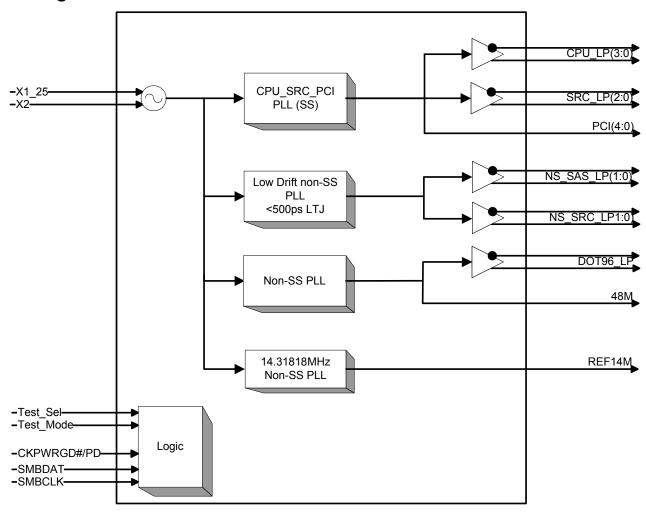
PIN#	PIN NAME	TYPE	DESCRIPTION			
1	GNDPCI	PWR	Ground pin for PCI outputs and logic.			
2	VDDPCI	PWR	3.3V power for the PCI outputs and logic			
3	PCI4_2x	OUT	3.3V PCI clock output			
4	PCI3_2x	OUT	3V PCI clock output			
5	PCI2_2x	OUT	3.3V PCI clock output			
6	PCI1_2x	OUT	3.3V PCI clock output			
7	PCI0_2x	OUT	3.3V PCI clock output			
8	GNDPCI	PWR	Ground pin for PCI outputs and logic.			
9	VDDPCI	PWR	3.3V power for the PCI outputs and logic			
10	VDD48		3.3V power for the 48MHz output and logic			
11	48M_2x	OUT	3.3V 48MHz output			
12	GND48	PWR	Ground pin for 48MHz output and logic.			
13	GND96	PWR	Ground pin for DOT96 output and logic.			
4.4	DOTOC LDT	OUT	True clock of low-power push-pull differential 96MHz output. External series resistors are needed			
14	DOT96_LPT	001	for termination.			
4.5	DOTOC LDC	OUT	Complementary clock of low-power push-pull differential 96MHz output. External series resistors			
15	DOT96_LPC	001	are needed for termination.			
16	AVDD96	PWR	3.3V power for the 48/96MHz PLL and the 96MHz output and logic			
17	TECT MODE		TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in test			
17	TEST_MODE	IN	mode. Refer to Test Clarification Table.			
			CKPWRGD# is an active low input used to sample latched inputs and allow the device to Power			
18	CKPWRGD#/PD	IN	Up. PD is an asynchronous active high input pin used to put the device into a low power state.			
			The internal clocks and PLLs are stopped.			
19	VDDSRC	PWR	3.3V power for the SRC outputs and logic			
-00			True clock of low-power push-pull differential SRC output. External series resistors are needed			
20	SRC0_LPT	OUT	for termination.			
01	CDC0 LDC	OUT	Complementary clock of low-power push-pull differential SRC output. External series resistors			
21	SRC0_LPC	OUT	are needed for termination.			
22	GNDSRC	PWR	Ground pin for SRC outputs and logic.			
22	SDC1 LDC	OUT	Complementary clock of low-power push-pull differential SRC output. External series resistors			
23	SRC1_LPC	001	are needed for termination.			
0.4	CDC4 LDT	OUT	True clock of low-power push-pull differential SRC output. External series resistors are needed			
24	SRC1_LPT	001	for termination.			
05	CDC0 LDC	OUT	Complementary clock of low-power push-pull differential SRC output. External series resistors			
25	SRC2_LPC	001	are needed for termination.			
00	CDC0 LDT	OUT	True clock of low-power push-pull differential SRC output. External series resistors are needed			
26	SRC2_LPT	001	for termination.			
27	VDDSRC	PWR	3.3V power for the SRC outputs and logic			
28	AVDD_SRC	PWR	3.3V power for the SRC PLL analog circuits			
29	GNDSRC	PWR	Ground pin for SRC outputs and logic.			
30	NC	N/A	No Connection.			
31	NS_SRC0_LPC	OUT	Complementary clock of low-power push-pull differential non-spreading SRC output. External			
31	NS_SHCU_LPC	001	series resistors are needed for termination.			
200	NC CDCO LDT	OUT	True clock of low-power push-pull differential non-spreading SRC output. External series resistors			
32	NS_SRC0_LPT	OUT	are needed for termination.			
00	NO ODOL LDO	OUT	Complementary clock of low-power push-pull differential non-spreading SRC output. External			
33	NS_SRC1_LPC	OUT	series resistors are needed for termination.			
0.4	NC CDC1 LDT	O. IT	True clock of low-power push-pull differential non-spreading SRC output. External series resistors			
34	NS_SRC1_LPT	OUT	are needed for termination.			
35	VDDNS	PWR	3.3V power for the Non-Spreading differential outputs outputs and logic			
36	GNDNS		Ground pin for non-spreading differential outputs and logic.			
			True clock of low-power push-pull differential non-spreading SAS output. External series resistors			
38	NS_SAS0_LPT	OUT	are needed for termination.			
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932SQL420

64MLF Pin Descriptions (cont.)

PIN#	PIN NAME	TYPE				
39	NS_SAS1_LPC	OUT	Complementary clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.			
40	NS_SAS1_LPT	OUT	rue clock of low-power push-pull differential non-spreading SAS output. External series resistors are needed for termination.			
41	AVDD_NS_SAS		3.3V power for the non-spreading SAS/SRC PLL analog circuits.			
42	GNDNS	PWR	Ground pin for non-spreading differential outputs and logic.			
43	CPU0_LPC	OUT	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
44	CPU0_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
45	CPU1_LPC	OUT	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
46	CPU1_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
47	VDDCPU	PWR	3.3V power for the CPU outputs and logic			
48	GNDCPU		Ground pin for CPU outputs and logic.			
49	CPU2_LPC	OUT	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
50	CPU2_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
51	CPU3_LPC	OUT	Complementary clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
52	CPU3_LPT	OUT	True clock of low-power push-pull differential CPU output. External series resistors are needed for termination.			
53	VDDCPU	PWR	3.3V power for the CPU outputs and logic			
54	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant			
55	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant			
56	GND14		Ground pin for 14MHz output and logic.			
57	AVDD14		Analog power pin for 14MHz PLL			
58	VDD14	PWR	Power pin for 14MHz output and logic			
59	vREF14_3x/TEST_SEL	I/O	14.318 MHz reference clock. 3X drive strength as default / TEST_SEL latched input to enable test mode. Refer to Test Clarification Table. This pin has a weak (~120Kohm) internal pull down.			
60	GND14		Ground pin for 14MHz output and logic.			
61	GNDXTAL	PWR	Ground pin for Crystal Oscillator.			
	X1_25	IN	Crystal input, Nominally 25.00MHz.			
	X2_25		Crystal output, Nominally 25.00MHz.			
64	VDDXTAL	PWR	3.3V power for the crystal oscillator.			

Block Diagram



Power Supply and Test Loads

Power Group Pin Numbers

MLI	F	TSSOP		Decemention	
VDD	GND	VDD	GND	Description	
57	56	3	2	14MHz PLL Analog	
58	60	4	6	REF14M Output and Logic	
64	61	10	7	25MHz XTAL	
2, 9	1, 8	12, 19	11, 18	PCI Outputs and Logic	
10	12	20	22	48MHz Output and Logic	
16	13	26	23	96MHz PLL Analog, Output and Logic	
19, 27	22	29, 37	32	SRC Outputs and Logic	
28	29	38	39	SRC PLL Analog	
35	36	45	46	Non-Spreading Differential Outputs & Logic	
41	42	51	52	NS-SAS/SRC PLL Analog	
47, 53	48	57,63	58	CPU Outputs and Logic	

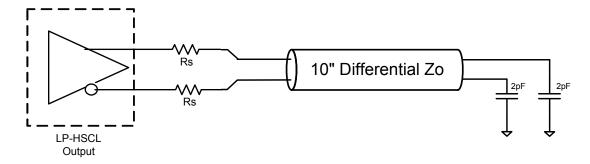
Single-ended Output Termination Table

		Rs Value		
		(for each load)		
Output	Loads	Zo = 50	Zo =60	
PCI/USB	1	36	43	
PCI/USB	2	22	33	
REF	1	39	47	
REF	2	27	36	
REF	3	10	20	

Differential Output Termination Table

DIF Zo (Ω)	Rs (Ω)
100	33
85	27

932SQL420 Differential Test Loads



Functionality and CPU SAS Frequency Tables

932SQL420 Functionality

				NS_SAS			
CPU	SRC	PCI	REF	NS_SRC	DOT96	USB	
100	100	33.33	14.318	100.00	96.00	48.00	MHz

Spread Spectrum Control Functionality

SS_Enable	CPU, SRC &		
(B1b0)	PCI		
0	OFF		
1	-0.50%		

932SQL420 Power Down Functionality

CKPWRGD#/PD	Differential Outputs	Single- ended Outputs	Single- ended Outputs w/Latch	
1	Low/Low	Low	Low ¹	
•		Runnina		

^{1.} Single-ended outputs with a Latch will be Hi-Z until the first application of CKPWRGD#.

CPU/SRC/PCI Margining Table

Line	Byte6 Bit2 FS2	Byte6 Bit1 FS1	Byte6 Bit0 FS0	CPU Speed (MHz)	SRC (MHz)	PCI (MHz)
0	0	0	0	97.00	97.00	32.33
1	0	0	1	98.00	98.00	32.67
2	0	1	0	99.00	99.00	33.00
3	0	1	1	100.00	100.00	33.33
4	1	0	0	101.00	101.00	33.67
5	1	0	1	102.00	102.00	34.00
6	1	1	0	103.00	103.00	34.33
7	1	1	1	104.00	104.00	34.67

NS_SAS Margining Table

Line	Byte5 Bit3 FS3	Byte5 Bit2 FS2	Byte5 Bit1 FS1	Byte5 Bit0 FS0	NS_xxx (MHz)
0	0	0	0	0	82.5
1	0	0	0	1	85.0
2	0	0	1	0	87.5
3	0	0	1	1	90.0
4	0	1	0	0	92.5
5	0	1	0	1	95.0
6	0	1	1	0	97.5
7	0	1	1	1	100.0
8	1	0	0	0	102.5
9	1	0	0	1	105.0
10	1	0	1	0	107.5
11	1	0	1	1	110.0
12	1	1	0	0	112.5
13	1	1	0	1	115.0
14	1	1	1	0	117.5
15	1	1	1	1	120.0

NOTE: Operation at other than the default entry is not guaranteed. These values are for margining purposes only.

Clock AC Tolerances

		NS_SAS,					
	CPU, SRC	NS_SRC	PCI	DOT96	48MHz	REF	
PPM tolerance	100	100	100	100	100	100	ppm
Cycle to Cycle Jitter	50	50	500	250	350	1000	ps
Spread	-0.50%	0.00%	-0.50%	0	0.00%	0.00%	%

Clock Periods-Outputs with Spread Spectrum Disabled

				Me	easurement W	indow				
	Center	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC OFF	Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
CPU	100.000	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2
SRC, NS_SAS, NS_SRC	100.000	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2
PCI	33.333	29.49700		29.99700	30.00000	30.00300		30.50300	ns	1,2
DOT96	96.000	10.16563		10.41563	10.41667	10.41771		10.66771	ns	1,2
48MHz	48.000	20.48125		20.83125	20.83333	20.83542		21.18542	ns	1,2
REF	14.318	69.78429		69.83429	69.84128	69.84826		69.89826	ns	1,2

Clock Periods-Outputs with Spread Spectrum Enabled

			Measurement Window							
	Center Freq. MHz	1 Clock	1us	0.1s	0.1s 0.1s 0.1s		1us	1 Clock		
SSC ON		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
CPU	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2
PCI	33.25	29.49718	29.99718	30.07218	30.07519	30.07820	30.15320	30.65320	ns	1,2
SRC	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the REF output is tuned to exactly 14.31818MHz.

General SMBus Serial Interface Information for 932SQL420

How to Write

- · Controller (host) sends a start bit
- · Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- · IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

	Index Block Write Operation									
Controll	er (Host)		IDT (Slave/Receiver)							
Т	starT bit									
Slave Add	ress D2 _(H)									
WR	WRite									
			ACK							
Beginning	Byte = N									
			ACK							
Data Byte	Count = X									
			ACK							
Beginnin	g Byte N									
			ACK							
0		×								
0		X Byte	0							
0		ė	0							
			0							
Byte N	Byte N + X - 1									
			ACK							
Р	stoP bit									

How to Read

- · Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- · Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- · Controller (host) will need to acknowledge each byte
- · Controller (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

	Index Block F	Read O	peration
Cor	ntroller (Host)		IDT (Slave/Receiver)
Т	starT bit		
Slave	Address D2 _(H)		
WR	WRite		
			ACK
Begi	nning Byte = N		
			ACK
RT	Repeat starT		
Slave	Slave Address D3 _(H)		
RD	ReaD		
			ACK
			Data Byte Count=X
	ACK		
			Beginning Byte N
	ACK		
		ē	0
	0	X Byte	0
	0	×	0
	0		
			Byte N + X - 1
N	Not acknowledge		
Р	stoP bit		

Read Address	Write Address
D3 _(H)	D2 _(H)

NOTE: Pin numbers refer to TSSOP

SMBus Table: Output Enable Register

Byte	0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	2	4/25	DOT96 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 6	5	0/49	NS_SAS1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 5	4	8/47	NS_SAS0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 4	4	4/43	NS_SRC1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 3	4	2/41	NS_SRC0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 2	3	6/35	SRC2 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 1	3	4/33	SRC1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 0	3	0/31	SRC0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1

SMBus Table: Output Enable Register

Byte	1 Pin#	Name	Control Function	Type	0	1	Default
Bit 7	5	REF14_3x Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 6			RESERVE)			0
Bit 5		RESERVED					
Bit 4	62/61	CPU3	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 3	60/59	CPU2	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 2	56/55	CPU1	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 1	54/53	CPU0	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 0	CPU/SRC/ PCI	Spread Spectrum Enable	Spread Off/On	RW	Spread Off	Spread On	0

SMBus Table: Output Enable Register

Byte	2 Pin #	Name	Control Function	Type	0	1	Default
Bit 7			RESERVE	D			0
Bit 6		RESERVED					
Bit 5	13	PCI4 Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 4	14	PCI3 Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 3	15	PCI2 Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 2	16	PCI1 Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 1	17	PCI0 Enable	Output Enable	RW	Disable-Low	Enable	1
Bit 0	21	48MHz Enable	Output Enable	RW	Disable-Low	Enable	1

SMBus Table: Differential Amplitude Control

Byte 3	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	CPU AMPLITUDE 1	CPU Vhigh	RW	00 = 700 mV	01 = 800mV	0
Bit 6		CPU AMPLITUDE 0	CPO Viligii	RW	10 = 900mV	11 = 1000mV	1
Bit 5		SRC AMPLITUDE 1	SDC Whigh	RW	00 = 700mV	01 = 800mV	0
Bit 4		SRC AMPLITUDE 0	SRC Vhigh	RW	10 = 900mV	11 = 1000mV	1
Bit 3		DOT96 AMPLITUDE 1	DOTOS Vhigh	RW	00 = 700mV	01 = 800mV	0
Bit 2		DOT96 AMPLITUDE 0	DOT96 Vhigh	RW	10 = 900mV	11 = 1000mV	1
Bit 1		NS-SAS/SRC AMPLITUDE 1	NC CAC/CDC Vbiab	RW	00 = 700mV	01 = 800mV	0
Bit 0		NS-SAS/SRC AMPLITUDE 0	NS-SAS/SRC Vhigh	RW	10 = 900mV	11 = 1000mV	1

SMBus Table: Spread Amount Register

	· • · • • · • •	ia Ainount riegiotei					
Byte 4	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			RESERVE)			0
Bit 6			RESERVEI)			0
Bit 5		RESERVED					0
Bit 4		RESERVED					
Bit 3			RESERVE)			0
Bit 2			RESERVEI)			0
Bit 1		SS AMOUNT[1]	Spread Amount (note	RW	00= -0.2%	10= -0.4%	1
Bit 0		SS AMOUNT[0]	B1b0 must be set to '1')	RW	01= -0.3%	11= -0.5%	1

11

SMBus Table: NS_SAS/NS_SRC Frequency Margining Table

Byte	5 Pin #	Name	Control Function	Type	0	1	Default			
Bit 7			RESERVED							
Bit 6			RESERVED							
Bit 5			RESERVED							
Bit 4		RESERVED								
Bit 3	-	FS3	Freq. Sel 3	RW			0			
Bit 2	-	FS2	Freq. Sel 2	RW	See NS_SAS/NS_	_SRC Frequency	1			
Bit 1	-	FS1	Freq. Sel 1	RW	Tab	le.	1			
Bit 0	-	FS0	Freq. Sel 0	RW			1			

SMBus Table: Test Mode and CPU/SRC/PCI Frequency Select Register

Byte	e 6 Pin #	Name	Control Function	Type	0	1	Default	
Bit 7		Test Mode	Test Mode Type	RW	Hi-Z	REF/N	0	
Bit 6	-	Test Select	Select Test Mode	RW	Disable	0		
Bit 5	•		RESERVE	D				
Bit 4	-		RESERVED					
Bit 3	•		RESERVE	D			0	
Bit 2	-	FS2	Freq. Sel 2	RW	See CPU/SRC/I	OCI Fraguenov	0	
Bit 1	-	FS1	Freq. Sel 1	RW	See CPU/ShC/i Select	1		
Bit 0	-	FS0	Freq. Sel 0	RW	Select	iable	1	

Note: Internal Pull up on 100M_133M# pin will result in default CPU frequency of 100 MHz.

SMBus Table: Vendor & Revision ID Register

OIIIDao Ta	3.01 T 0.14	or a rievicien iz megicier					
Byte 7	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3		R			0
Bit 6	-	RID2	REVISION ID	R	1 for l	0	
Bit 5	-	RID1	(1h forB rev)	R	1 101 1	0	
Bit 4	-	RID0		R		1	
Bit 3	-	VID3		R			0
Bit 2	-	VID2	VENDOR ID	R	0001 for ICS/IDT		0
Bit 1	-	VID1	A SEINDOR ID	R			0
Bit 0	-	VIDO	1	R			1

SMBus Table: Byte Count Register

Byte 8	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	BC7		RW			0
Bit 6	-	BC6		RW]		0
Bit 5	-	BC5		RW	Writing to this regis	ster will configure	0
Bit 4	-	BC4	Byte Count	RW	how many bytes v	0	
Bit 3	-	BC3	Programming b(7:0)	RW	default is	A bytes.	1
Bit 2	-	BC2		RW	(0 to	9	0
Bit 1	-	BC1		RW]		1
Bit 0	-	BC0		RW			0

SMBus Table: Device ID Register

Byte 9	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	•	DID7		R	•	•	0
Bit 6		DID6		R	•	-	1
Bit 5		DID5		R	-	•	0
Bit 4		DID4	Device ID	R	-	-	0
Bit 3		DID3	(42 hex)	R	-	-	0
Bit 2		DID2		R	-	-	0
Bit 1		DID1		R	-	-	1
Bit 0	•	DID0		R	-	-	0

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 932SQL420. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA				4.6	٧	1,2
3.3V Logic Supply Voltage	VDD				4.6	٧	1,2
Input Low Voltage	V_{IL}		GND-0.5			٧	1
Input High Voltage	V_{IH}	Except for SMBus interface			V _{DD} +0.5V	V	1
Input High Voltage	V_{IHSMB}	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Case Temperature	Тс				110	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Current Consumption

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I _{DD3.3OP}	All outputs active @100MHz, $C_L = Full load;$			250	mA	1
Powerdown Current	I _{DD3.3PDZ}				6	mA	1

¹Guaranteed by design and characterization, not 100% tested in production.

AC Electrical Characteristics—Differential Current Mode Outputs

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45		55	%	1
Skew, Output to Output	t _{sk3SRC}	Across all SRC outputs, $V_T = 50\%$			50	ps	1
Skew, Output to Output	t _{sk3CPU}	Across all CPU outputs, $V_T = 50\%$			50	ps	1
Jitter, Cycle to cycle	t.	CPU, SRC, NS_SAS outputs			50	ps	1,3
officer, Cycle to Cycle	τ _{jcyc-cyc}	DOT96 output			250	ps	1,3

¹Guaranteed by design and characterization, not 100% tested in production.

² Operation under these conditions is neither implied nor guaranteed.

² Zo=85 Ω (differential impedance).

³ Measured from differential waveform

Electrical Characteristics-Input/Supply/Common Parameters

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating							
Temperature	T _{COM}	Commmercial range	0		70	°C	1
Input High Voltage	V _{IH}	Single-ended inputs, except SMBus, low threshold and tri- level inputs	2		V _{DD} + 0.3	V	1
Input Low Voltage	V_{IL}	Single-ended inputs, except SMBus, low threshold and tri- level inputs	GND - 0.3		0.8	V	1
	I _{IN}	Single-ended inputs, $V_{IN} = GND, V_{IN} = VDD$	-5		5	uA	1
Input Current	I _{INP}	Single-ended inputs. V _{IN} = 0 V; Inputs with internal pull-up resistors V _{IN} = VDD; Inputs with internal pull-down resistors	-200		200	uA	1
Low Threshold Input- High Voltage	V_{IH_FS}	3.3 V +/-5%	0.7		V _{DD} + 0.3	V	1
Low Threshold Input- Low Voltage	V_{IL_FS}	3.3 V +/-5%	V _{SS} - 0.3		0.35	V	1
Input Frequency	F_i			25.00		MHz	2
Pin Inductance	L_{pin}				7	nΗ	1
	C _{IN}	Logic Inputs			5	рF	1
Capacitance	C _{OUT}	Output pin capacitance			5	pF	1
	C _{INX}	X1 & X2 pins			5	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or deassertion of PD# to 1st clock			1.8	ms	1,2
SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30	31.5	33	kHz	1
Tdrive_PD#	t _{DRVPD}	Differential output enable after PD# de-assertion			300	us	1,3
Tfall	t _F	Fall time of control inputs			5	ns	1,2
Trise	t_R	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	V_{ILSMB}				0.8	V	1
SMBus Input High Voltage	V_{IHSMB}		2.1		V_{DDSMB}	V	1
SMBus Output Low Voltage	V_{OLSMB}	@ I _{PULLUP}			0.4	V	1
SMBus Sink Current	I _{PULLUP}	@ V _{OL}	4			mA	1
Nominal Bus Voltage	$V_{\rm DDSMB}$	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

 $^{^3}$ Time from deassertion until outputs are >200 mV

DC Electrical Characteristics-Differential Current Mode Outputs

 $T_A = T_{COM}$: Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on	1		4	V/ns	1, 2, 3
Slew rate matching	∆dV/dt	Slew rate matching, Scope averaging on			20	%	1, 2, 4
Rise/Fall Time Matching	ΔTrf	Rise/fall matching, Scope averaging off			125	ps	1, 8, 9
Voltage High	VHigh	Statistical measurement on single-ended signal using	660		850	mV	1
Voltage Low	VLow	oscilloscope math function. (Scope averaging on)	-150		150	IIIV	1
Max Voltage	Vmax	Measurement on single ended			1150	mV	1, 7
Min Voltage	Vmin	signal using absolute value.	-300			IIIV	1, 7
Vswing	Vswing	Scope averaging off	300			mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250		550	mV	1, 5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off			140	mV	1, 6

¹Guaranteed by design and characterization, not 100% tested in production. $Z_0=85\Omega$ (differential impedance).

Electrical Characteristics-48MHz

 $T_A = 0 - 70^{\circ}C$; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V } +/-5\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	20		60	Ω	1
Output High Voltage	V_{OH}	$I_{OH} = -1 \text{ mA}$	2.4			V	1
Output Low Voltage	V_{OL}	I _{OL} = 1 mA			0.55	V	1
Output High Current	_	MIN @V _{OH} = 1.0 V	-29			mA	1
Output High Current	Гон	MAX @V _{OH} = 3.135 V			-33	mA	1
Output Low Current	_	MIN @V _{OL} = 1.95 V	29			mA	1
Output Low Current	I _{OL}	MAX @ $V_{OL} = 0.4 V$			27	mA	1
Clock High Time	T _{HIGH}	1.5V	8.094		10.036	ns	1
Clock Low Time	T_LOW	1.5V	7.694		9.836	ns	1
Edge Rate	t _{slewr/f_USB}	Rising/Falling edge rate	1		2	V/ns	1,2
Duty Cycle	d _{t1}	$V_{T} = 1.5 V$	45		55	%	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	V _T = 1.5 V			350	ps	1

See "Power Supply and Test Loads" page for termination circuits

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of V_cross_min/max (V_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V_cross_delta to be smaller than

⁷ Includes overshoot and undershoot.

⁸ Measured from single-ended waveform

⁹ Measured with scope averaging off, using statistics function. Variation is difference between min and max.

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V

Electrical Characteristics-Phase Jitter Parameters

 $T_A = 0 - 70^{\circ}C$; Supply Voltage $V_{DD}/V_{DDA} = 3.3 \text{ V } +/-5\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
	t _{iphPCleG1}	PCIe Gen 1			86	ps (p-p)	1,2,3,6
		PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz			3	ps (rms)	1,2,6
	t _{jphPCleG2}	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)			3.1	ps (rms)	1,2,6
	t _{jphPCleG3}	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)			1	ps (rms)	1,2,4,6
Phase Jitter	t _{jphQPI_SMI}	QPI & SMI (100MHz, 4.8Gb/s, 6.4Gb/s 12UI)			0.5	ps (rms)	1,5,7
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)			0.3	ps (rms)	1,5,7
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)			0.2	ps (rms)	1,5,7
	t _{jphSAS12G}	SAS 12G			1.3	ps (rms)	1,5,8

¹ Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-PCI

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V +/-5\%}$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	12		55	Ω	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V_{OL}	$I_{OL} = 1 \text{ mA}$			0.55	V	1
Output High Current		MIN @V _{OH} = 1.0 V	-33			mA	1
Output High Current	Гон	MAX @V _{OH} = 3.135 V			-33	mA	1
Output Low Current	_	MIN @V _{OL} = 1.95 V	30			mA	1
Output Low Current	I _{OL}	MAX @ $V_{OL} = 0.4 V$			38	mA	1
Clock High Time	T _{HIGH}	1.5V	12			ns	1
Clock Low Time	T_LOW	1.5V	12			ns	1
Edge Rate	t _{slewr/f}	Rising/Falling edge rate	1		4	V/ns	1,2
Duty Cycle	d _{t1}	$V_{T} = 1.5 V$	45		55	%	1
Group Skew	t _{skew}	$V_{T} = 1.5 V$			500	ps	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	V _T = 1.5 V			500	ps	1

See "Power Supply and Test Loads" page for termination circuits

² See http://www.pcisig.com for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ Subject to final radification by PCI SIG.

⁵ Calculated from Intel-supplied Clock Jitter Tool v 1.6.6

⁶ Applied to SRC outputs

⁷ Applies to CPU outputs

⁸ Applies to NS_SAS, NS_SRC outputs, Spread Off

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V

Electrical Characteristics-REF

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V +/-5}\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	12		55	Ω	1
Output High Voltage	V_{OH}	$I_{OH} = -1 \text{ mA}$	2.4			V	1
Output Low Voltage	V_{OL}	$I_{OL} = 1 \text{ mA}$			0.55	V	1
Output High Current	I _{OH}	MIN @V _{OH} = 1.0 V	-33			mA	1
		MAX $@V_{OH} = 3.135 \text{ V}$			-33	mA	1
Output Low Current	I _{OL}	MIN $@V_{OL} = 1.95 \text{ V}$	30			mA	1
		MAX @ V _{OL} = 0.4 V			38	mA	1
Clock High Time	T _{HIGH}	1.5V	27.5			ns	1
Clock Low Time	T_LOW	1.5V	27.5			ns	1
Edge Rate	t _{slewr/f}	Rising/Falling edge rate	1		4	V/ns	1,2
Duty Cycle	d _{t1}	V _T = 1.5 V	45		55	%	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	V _T = 1.5 V			1000	ps	1

See "Power Supply and Test Loads" page for termination circuits

Test Clarification Table

Comments	HW		SW		
	TEST_SEL HW PIN	TEST_MOD E HW PIN	TEST ENTRY BIT B6b6	REF/N or HI-Z B6b7	ОИТРИТ
	0	Χ	0	Χ	NORMAL
Power-up w/ TEST_SEL = 1 (>2.0V) to enter test	1	0	Χ	0	HI-Z
mode. Cycle power to disable test mode.	1	0	Χ	1	REF/N
mode. Cycle power to disable test mode.	1	1	Χ	0	REF/N
	1	1	Χ	1	REF/N
	0	Χ	1	0	HI-Z
If TEST_SEL HW pin is 0 during power-up, test mode can be selected through B6b6. If test mode is selected by B6b6, then B6b7 is used to select HI-Z or REF/N FS_B/TEST_Mode pin is not used. Cycle power to disable test mode.	0	X	1	1	REF/N

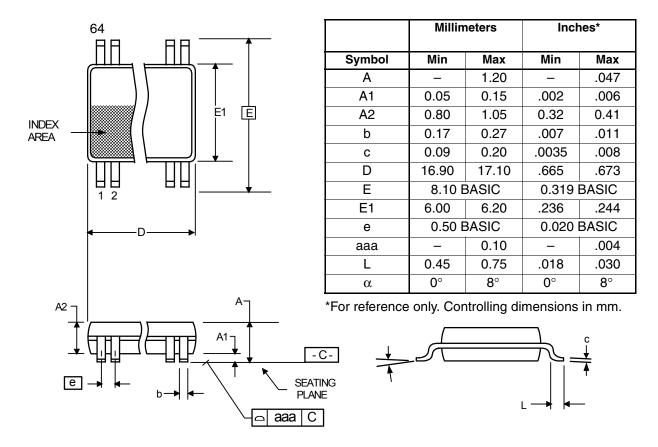
B6b6: 1= ENTER TEST MODE, Default = 0 (NORMAL OPERATION)

B6b7: 1 = REF/N, Default = 0 (HI-Z)

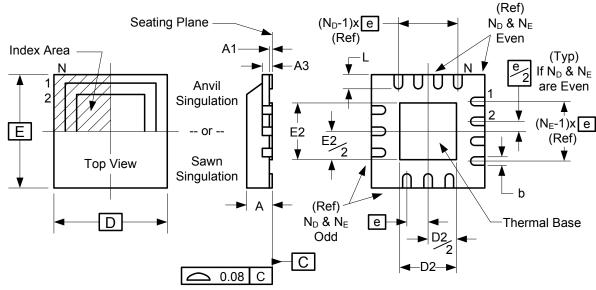
¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V

Package Outline and Package Dimensions (64-pin TSSOP)



Package Outline and Package Dimensions (64-pin MLF)



	Millimeters			
Symbol	Min	Max		
Α	0.8	1.0		
A1	0	0.05		
A3	0.25 Re	ference		
b	0.18	0.3		
е	0.50 E	BASIC		
D x E BASIC	9.00 >	¢ 9.00		
D2 MIN./MAX.	6.00	6.25		
E2 MIN./MAX.	6.00	6.25		
L MIN./MAX.	0.30	0.50		
N	6	4		
N_D	1	6		
N⊨	1	6		

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature	
932SQL420BGLF	Tubes	64-pin TSSOP	0 to +70° C	
932SQL420BGLFT	Tape and Reel	64-pin TSSOP	0 to +70° C	
932SQL420BKLF	Tray	64-pin MLF	0 to +70° C	
932SQL420BKLFT	Tape and Reel	64-pin MLF	0 to +70° C	

[&]quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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[&]quot;B" is the device revision designator (will not correlate with the datasheet revision).

Revision History

Rev.	Issue Date	Who	Description	Page #		
0.1	4/26/2010	RDW	Initial Release	-		
0.2	6/3/2010	RDW	Updated block diagram to remove the IREF resistor.			
0.3 10/24/2011		1 RDW	Updated power management table for Low Power Outputs (LPO)			
	10/24/2011		Updated SMBus for LPO disabled state	Various		
			Updated electrical tables with latest CK420BQ tables.			
0.4 12/5/2011		RDW	Updated frequency tables to match AP336 PLL programming			
	12/5/2011		2. Added dif output amplitude control to Byte 3	Various		
		TIDVV	3. Updated bytes 5 and 6 to reflect new frequency tables.	Various		
			4. Updated bytes 11-45 to reflect PLL control registers and test bytes.			
		/19/2012 RDW	Updated CPU/SRC/PCI Margining Table			
0.5 1/19/2012	1/19/2012		Updated NS_SAS Margining Table	Various		
	1/13/2012		3. Updated Current Consumption Table	Various		
			Updated General Description and Output Features Table			
0.6	3/27/2012	RDW	Updated ordering information to B rev	Various		
0.0 3/21/2012	3/21/2012 HDW	11011	Updated Rev ID in SMBus to reflect this.	Various		
	4/16/2012 RDW		Removed support for 133M on CPU			
			a. 48M output becomes Output only and not latched			
0.7 4/16/2012			b. B6[4] is now reserved and has default value of '1'.			
			c. CPU frequency table now reduced to 8 entries.			
		1/16/2012 RDW	2. DOT96 and NS_SAS/SRC amplitude bit are swapped to match A rev	Various		
		4/10/2012	1710/2012		silicon (B3[3:2] and B2[1:0])	Various
			3. 4 selectable spread amounts are added with control bits in B4[1:0].			
			i. See these bits for definition.			
				4. Differential output test loads now indicate Rs instead of specific value		
			to allow for 100ohm or 85ohm terminations.			
0.8 6/20/	6/20/2012 F	6/20/2012 RDW		1. Updated Vendor ID/Revision ID byte from 0000 0001 to 0001 0001	Various	
			Updated ordering information from AGLF/AKLF to BGLF/BKLF	Lanouo		

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